CLAIMS

1. A resin sheet for sealing an electronic device, which has a thickness of 100 to 2,000 μm and generates gas in an amount of 500 ppm or less when the resin sheet is cured at 150°C for 1 hour~~.~~

~~2. The resin sheet for sealing an electronic device according to claim 1~~,

wherein a cured product that is obtained by curing the resin sheet ~~for sealing an electronic device~~ at 150°C for 1 hour has a 1% weight reduction temperature of 260°C or higher.

2~~3~~. A~~The~~ resin sheet for sealing an electronic device ~~according to claim 1 or 2~~, which has a thickness of 100 to 2,000 μm and generates gas in an amount of 500 ppm or less when the resin sheet is cured at 150°C for 1 hour,

wherein an~~the~~ amount of gas is 500 ppm or less which is generated when a~~the~~ cured product that is obtained by curing the resin sheet ~~for sealing an electronic device~~ at 150°C for 1 hour is heated from 40°C to 260°C at a rising temperature rate of 10°C/min and then heated at 260°C for 1 minute.

3~~4~~. A method of manufacturing an electronic device package, the method comprising:

a lamination step of laminating the resin sheet for sealing an electronic device according to ~~any of~~ claim~~s~~ 1

or~~to~~ 2~~3~~ on one or a plurality of electronic devices so as to cover the electronic devices; and

a sealing body formation step of curing the resin sheet for sealing an electronic device to form a sealing body.

4. A method of manufacturing a resin sheet for sealing an electronic device, the method comprising:

kneading an epoxy resin, a phenol resin, a thermoplastic resin, an inorganic filler and a curing accelerator to prepare a kneaded product,

subjecting the kneaded product to plastic processing to form the kneaded product into a sheet shape,

wherein the resin sheet has a thickness of 100 to 2,000 μm and generates gas in an amount of 500 ppm or less when the resin sheet is cured at 150°C for 1 hour,

wherein a cured product that is obtained by curing the resin sheet at 150°C for 1 hour has a 1% weight reduction temperature of 260°C or higher.

5. A method of manufacturing a resin sheet for sealing an electronic device, the method comprising:

kneading an epoxy resin, a phenol resin, a thermoplastic resin, an inorganic filler and a curing accelerator to prepare a kneaded product,

subjecting the kneaded product to plastic processing to form the kneaded product into a sheet shape,

wherein the resin sheet has a thickness of 100 to 2,000 μm and generates gas in an amount of 500 ppm or less when the resin sheet is cured at 150°C for 1 hour,

wherein an amount of gas is 500 ppm or less which is generated when a cured product that is obtained by curing the resin sheet at 150°C for 1 hour is heated from 40°C to 260°C at a rising temperature rate of 10°C/min and then heated at 260°C for 1 minute.